

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1025	361/792.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:32
S2	105	S1 and (organic and ceramic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:32
S3	3850	361/762,761,764,795,792.ccls. or 174/256,258.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:55
S4	553	S3 and organic and ceramic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:55
S5	55	S3 and (heatsink or heat\$sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:57
S6	6	S4 and (heatsink or heat\$sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 10:01
S7	4	"6180436".pn. "6365964".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 10:01
S8	1161	(ceramic near substrate) and (organic near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 10:14

S9	603	S8 and (pcb or "circuit board")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 10:59
S10	0	174/255-259,252	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:00
S11	4356	174/255-259,252.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:01
S12	2322	S11 and (cermanic or non\$organic "metal oxide" "metal nitride" oxide nitride organic plastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:26
S13	1730	S12 and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:12
S14	1411	S13 and (conductor or wire or trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:12
S15	1231	S14 and @pd<"20040401"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:27
S16	824	S11 and (cermanic or non\$organic "metal oxide" "metal nitride" oxide nitride) and (organic plastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:27

S17	720	S16 and @pd<"20040401"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:27
S18	581	S17 and (conductor wire trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:36
S19	0	(ceramic and organi).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:36
S20	2866	(ceramic and organic).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:36
S21	434	S20 and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:42
S22	28	S21 and (pcb or "circuit board")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:37
S23	5481	(organic with ceramic with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:42
S24	574	S23 same (pcb or "circuit board")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:33

S25	5788	428/209,210,901.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 14:25
S26	455	S25 and (ceramic with organic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 14:28
S27	763999	chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:14
S28	27	("5036431" "5311402" "5481435" "5614766").PN. OR ("5936843").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/05 08:23
S29	20	("5072075" "5483421" "5491303" "5574630" "5615087" "5689091" "5808873" "5815374" "5894173" "5900675" "5936843" "5962922" "6137062" "6162997" "6163462" "6239980" "6271478" "6288347" "6335495").PN. OR ("6538213").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/05 08:28
S30	5481	(organic with ceramic with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:34
S31	574	S30 same (pcb or "circuit board")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:34
S32	450	S31 and component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:43

S33	116	S31 same component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:38
S34	1223090	S32 and (traces or conductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:43
S35	321	S32 and (traces or conductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:57
S36	5788	428/209,210,901.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:57
S37	175	S36 and S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:57
S38	23	("4680220" "4810563" "4849284" "4882455" "5061548" "5139852" "5213878" "5277725" "5287619" "5358775" "5384181" "5541249" "5552210" "5571609" "5670262" "5733640" "5919546" "5922453" "5965273").PN. OR ("6528145").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/05 08:58
S39	4	"power integrated circuit chip" with "ceramic substrate"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 09:35
S40	0	10/708935	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 09:47

S41	0	"10708935"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 09:47
S42	0	"10/708935"	US-PGPUB	OR	ON	2005/10/05 09:48
S43	15	oman.inv.	US-PGPUB	OR	ON	2005/10/05 09:49
S44	8	degenkolb.inv.	US-PGPUB	OR	ON	2005/10/05 09:49
S45	9298479	(ceramic near substrate) with (organic near substrate) with (adjacent or beside or parallel or connected)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 10:27
S46	6	(ceramic near substrate) with (organic near substrate) with (adjacent or beside or parallel or connected)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 10:27